Amendments to the Specification

Please replace paragraph **[0002]** with the following amended paragraph:

[0002] This application is related to U.S. Application No. U.S. Application No. 10/681,735, titled "Semiconductor multi-package module having inverted land grid array (LGA) package stacked over ball grid array (BGA) package"; U.S. Application No. 10/681,833, titled "Semiconductor stacked multi-package module having inverted second package and electrically shielded first package" which issued August 23, 2005 as U.S. Patent No. 6,933,598; U.S. Application No. 10/681,583, titled "Semiconductor multi-package module having inverted second package stacked over die-down flip-chip ball grid array (BGA) package"; U.S. Application No. 10/681,747, titled "Semiconductor multi-package module having inverted second package stacked over die-up flip-chip ball grid array (BGA) package" which issued June 14, 2005 as U.S. Patent No. 6,906,416; U.S. Application No. 10/681,584, titled "Semiconductor multi-package module having inverted second package and including additional die or stacked package on second package"; U.S. Application No. 10/681,734, titled "Semiconductor multi-package module having inverted bump chip carrier second package"; all filed 8 October 2003, and each of which is hereby incorporated by reference.